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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/032,318	12/21/2001	Bulent M. Basol	042496/0273335 NT-239	4666
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Pillsbury Winthrop LLP Intellectual Property Group 1600 Tysons Boulevard McLean, VA 22102			EXAMINER PARSONS, THOMAS H	
			ART UNIT	PAPER NUMBER
			1745	

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Please find below and/or attached an Office communication concerning this application or proceeding.

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APPLICATION NO./ CONTROL NO.	FILING DATE	FIRST NAMED INVENTOR / PATENT IN REEXAMINATION	ATTORNEY DOCKET NO.
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EXAMINER

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Commissioner for Patents

The information disclosure statement (IDS) submitted 7 May 2004 was filed after the mailing of the Notice of Allowance on 24 February 2004. The submission is in compliance with the provisions of 37 CFR 1.97. Accordingly, the information disclosure statement has been considered. Further, the IDS does not raise an issue of patentability.

The following is in regards to references that were listed as X references in the International Search Report filed as part of the IDS.

U.S. Patent No. 5,865,984 discloses an electrochemical etching method and an apparatus for removing conductive metal from the surface of a semiconductor wafer, wherein a nozzle is positioned opposite the center of the wafer surface and caused to move either linearly toward the perimeter or both linearly and rotationally wherein the nozzle sprays or impinges an etchant onto the wafer. Further, in operation, one of the fixture (including the wafer) and the nozzle are rotated. The wafer may be rotated while the nozzle is moved linearly, or the nozzle may be articulated so that the nozzle moves linearly while simultaneously moving in a circular position so that the workpiece is spirally etched.

WO 00/03426 discloses an apparatus for polishing a metal layer formed on a wafer comprising an electrolyte, a polishing receptacle, a wafer chuck, a fluid inlet, and at least one cathode. The wafer chuck holds and positions the wafer within the polishing receptacle. The electrolyte is delivered through the fluid inlet into the polishing receptacle. The cathode then applies an electropolishing current to the electrolyte to electropolish the wafer. Accordingly, discrete portions of the wafer can be electropolished to enhance uniformity of the electropolished wafer.

In contrast, claimed invention is concerned with a method and apparatus for removing conductive material from a bevel edge of a conductive layer of a workpiece comprising directing a continuous stream of etching solution to the bevel edge of the workpiece, including a front edges surface of the conductive layer.

Neither of the X references teach or suggest such a method and apparatus as set forth in the claims of the instant application. Nor would it have been obvious to one skilled in the art at the time the invention was made to have modified the prior art nozzles that are adapted to electroetch or electropolish water surfaces to provide the claimed nozzles adapted to direct etchant to a bevel edged for removing a metal layer therefrom.

Attached is a signed copy of the IDS.

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Patrick Ryan
SPB rAD1745